1. General description

Trench Maximum Efficiency General Application (MEGA) Schottky barrier rectifier encapsulated in a CFP3 (SOD123W) small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 3$ A
- Reverse voltage: $V_R \leq 60$ V
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- High power capability due to clip-bonding technology
- Small and flat lead SMD power plastic package
- Capable for reflow and wave soldering
- AEC-Q101 qualified

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Freewheeling application
- Reverse polarity protection
- Low power consumption application

4. Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_{F(AV)}$</td>
<td>average forward current</td>
<td>$\delta = 0.5; f = 20$ kHz; $T_{sp} \leq 147$ °C; square wave</td>
<td>-</td>
<td>-</td>
<td>3</td>
<td>A</td>
</tr>
<tr>
<td>$V_R$</td>
<td>reverse voltage</td>
<td>$T_J = 25$ °C</td>
<td>-</td>
<td>-</td>
<td>60</td>
<td>V</td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 3$ A; pulsed; $T_J = 25$ °C [1]</td>
<td>-</td>
<td>550</td>
<td>620</td>
<td>mV</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 10$ V; pulsed; $T_J = 25$ °C [1]</td>
<td>-</td>
<td>0.14</td>
<td>0.9</td>
<td>$\mu$A</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 60$ V; pulsed; $T_J = 25$ °C [1]</td>
<td>-</td>
<td>0.3</td>
<td>1.8</td>
<td>$\mu$A</td>
</tr>
</tbody>
</table>

[1] Very short pulse, in order to maintain a stable junction temperature.
5. Pinning information

Table 2. Pinning information

<table>
<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>K</td>
<td>cathode</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>A</td>
<td>anode</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

6. Ordering information

Table 3. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Description</th>
<th>Version</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMEG60T30ELR</td>
<td>CFP3</td>
<td>plastic, surface mounted package; 2 terminals; 2.6 mm x 1.7 mm x 1 mm body</td>
<td>SOD123W</td>
</tr>
</tbody>
</table>

7. Marking

Table 4. Marking codes

<table>
<thead>
<tr>
<th>Type number</th>
<th>Marking code</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMEG60T30ELR</td>
<td>L8</td>
</tr>
</tbody>
</table>
8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>V_R</td>
<td>reverse voltage</td>
<td>T_j = 25 °C</td>
<td>-</td>
<td>60</td>
<td>V</td>
</tr>
<tr>
<td>I_F</td>
<td>forward current</td>
<td>δ = 1; T_sp ≤ 140 °C</td>
<td>-</td>
<td>4.2</td>
<td>A</td>
</tr>
<tr>
<td>I_F(AV)</td>
<td>average forward current</td>
<td>δ = 0.5; f = 20 kHz; T_sp ≤ 147 °C; square wave</td>
<td>-</td>
<td>3</td>
<td>A</td>
</tr>
<tr>
<td>I_FSM</td>
<td>non-repetitive peak forward current</td>
<td>t_p = 8 ms; square wave; T_j(init) = 25 °C</td>
<td>-</td>
<td>60</td>
<td>A</td>
</tr>
<tr>
<td>P_tot</td>
<td>total power dissipation</td>
<td>T_amb ≤ 25 °C</td>
<td>[1]</td>
<td>0.68</td>
<td>W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[2]</td>
<td>1.15</td>
<td>W</td>
</tr>
<tr>
<td>T_j</td>
<td>junction temperature</td>
<td></td>
<td>-</td>
<td>175</td>
<td>°C</td>
</tr>
<tr>
<td>T_amb</td>
<td>ambient temperature</td>
<td></td>
<td>-55</td>
<td>175</td>
<td>°C</td>
</tr>
<tr>
<td>T_stg</td>
<td>storage temperature</td>
<td></td>
<td>-65</td>
<td>175</td>
<td>°C</td>
</tr>
</tbody>
</table>


9. Thermal characteristics

Table 6. Thermal characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>R_th(j-a)</td>
<td>thermal resistance from junction to ambient</td>
<td>in free air</td>
<td>[1]</td>
<td>[3]</td>
<td>220</td>
<td>K/W</td>
</tr>
<tr>
<td>R_th(j-sp)</td>
<td>thermal resistance from junction to solder point</td>
<td></td>
<td>[1]</td>
<td>[3]</td>
<td>130</td>
<td>K/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[4]</td>
<td></td>
<td>18</td>
<td>K/W</td>
</tr>
</tbody>
</table>

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
FR4 PCB, standard footprint

**Fig. 1.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

FR4 PCB, mounting pad for cathode 1 cm²

**Fig. 2.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
## 10. Characteristics

### Table 7. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{(BR)R}$</td>
<td>reverse breakdown voltage</td>
<td>$I_R = 1 \text{ mA};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>60</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 0.1 \text{ A};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>380</td>
<td>450</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 0.5 \text{ A};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>440</td>
<td>510</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 1 \text{ A};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>470</td>
<td>540</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 2 \text{ A};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>515</td>
<td>590</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 3 \text{ A};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>550</td>
<td>620</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 3 \text{ A};$ pulsed; $T_j = -40 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>610</td>
<td>-</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 10 \text{ V};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>0.14</td>
<td>0.9</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 40 \text{ V};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>0.18</td>
<td>-</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 60 \text{ V};$ pulsed; $T_j = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>0.3</td>
<td>1.8</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 60 \text{ V};$ pulsed; $T_j = 125 ^\circ \text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>480</td>
<td>-</td>
</tr>
<tr>
<td>$C_d$</td>
<td>diode capacitance</td>
<td>$V_R = 1 \text{ V};$ $f = 1 \text{ MHz};$ $T_j = 25 ^\circ \text{C}$</td>
<td>-</td>
<td>580</td>
<td>-</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 10 \text{ V};$ $f = 1 \text{ MHz};$ $T_j = 25 ^\circ \text{C}$</td>
<td>-</td>
<td>180</td>
<td>-</td>
<td>pF</td>
</tr>
<tr>
<td>$t_{rr}$</td>
<td>reverse recovery time</td>
<td>$I_F = 0.5 \text{ A};$ $I_R = 0.5 \text{ A};$ $I_R(\text{meas}) = 0.1 \text{ A};$ $T_j = 25 ^\circ \text{C}$</td>
<td>-</td>
<td>17</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td></td>
<td></td>
<td>ramp recovery</td>
<td>-</td>
<td>16</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>$V_{FRM}$</td>
<td>peak forward recovery voltage</td>
<td>$I_F = 0.5 \text{ A};$ $dI_F/dt = 200 \text{ A/µs};$ $V_R = 26 \text{ V};$ $T_j = 25 ^\circ \text{C}$</td>
<td>-</td>
<td>460</td>
<td>-</td>
<td>mV</td>
</tr>
</tbody>
</table>

[1] Very short pulse, in order to maintain a stable junction temperature.
Fig. 3. Forward current as a function of forward voltage; typical values

- Pulsed condition
  - (1) $T_J = 175 \, ^\circ C$
  - (2) $T_J = 150 \, ^\circ C$
  - (3) $T_J = 125 \, ^\circ C$
  - (4) $T_J = 100 \, ^\circ C$
  - (5) $T_J = 85 \, ^\circ C$
  - (6) $T_J = 25 \, ^\circ C$
  - (7) $T_J = -40 \, ^\circ C$

Fig. 4. Reverse current as a function of reverse voltage; typical values

- Pulsed condition
  - (1) $T_J = 175 \, ^\circ C$
  - (2) $T_J = 150 \, ^\circ C$
  - (3) $T_J = 125 \, ^\circ C$
  - (4) $T_J = 100 \, ^\circ C$
  - (5) $T_J = 85 \, ^\circ C$
  - (6) $T_J = 25 \, ^\circ C$
  - (7) $T_J = -40 \, ^\circ C$

Fig. 5. Diode capacitance as a function of reverse voltage; typical values

- $f = 1 \, MHz, T_{amb} = 25 \, ^\circ C$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values

- $T_J = 100 \, ^\circ C$
  - (1) $\delta = 0.1$
  - (2) $\delta = 0.2$
  - (3) $\delta = 0.5$
  - (4) $\delta = 0.8$
  - (5) $\delta = 1; DC$
T_j = 100 °C
(1) δ = 1; DC
(2) δ = 0.9
(3) δ = 0.8
(4) δ = 0.5
(5) δ = 0.2

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values

FR4 PCB, standard footprint
T_j = 175 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values

FR4 PCB, mounting pad for cathode 1 cm²
T_j = 175 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values

T_j = 175 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values
11. Test information

Fig. 11. Reverse recovery definition; step recovery

Fig. 12. Reverse recovery definition; ramp recovery

Fig. 13. Forward recovery definition
Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

\[ I_{F(AV)} = I_M \times \delta \] with \( I_M \) defined as peak current,

\[ I_{RMS} = I_{F(AV)} \text{ at DC, and } I_{RMS} = I_M \times \sqrt{\delta} \]

with \( I_{RMS} \) defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

Fig. 15. Package outline CFP3 (SOD123W)
13. Soldering

Fig. 16. Reflow soldering footprint for CFP3 (SOD123W)
60 V, 3 A low leakage current Trench MEGA Schottky barrier rectifier

Wave soldering footprint information

occupied area
solder resist
solder lands
dummy track (solder resist and Cu free)

Dimensions in mm

Issue date
17-06-06
17-06-07

sod123w_fw

Fig. 17. Wave soldering footprint for CFP3 (SOD123W)
14. Revision history

Table 8. Revision history

<table>
<thead>
<tr>
<th>Data sheet ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMEG60T30ELR v.2</td>
<td>20180524</td>
<td>Product data sheet</td>
<td>-</td>
<td>PMEG60T30ELR v.1</td>
</tr>
<tr>
<td>Modifications:</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>• Product status</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>changed</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PMEG60T30ELR v.1</td>
<td>20180227</td>
<td>Preliminary data sheet</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>
15. Legal information

Data sheet status

<table>
<thead>
<tr>
<th>Document status</th>
<th>Product status</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>Objective [short] data sheet</td>
<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
</tr>
<tr>
<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
</tr>
<tr>
<td>Product [short] data sheet</td>
<td>Production</td>
<td>This document contains the product specification.</td>
</tr>
</tbody>
</table>

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term ‘short data sheet’ is explained in section “Definitions.”
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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For more information, please visit: http://www.nexperia.com
For sales office addresses, please send an email to: salesaddresses@nexperia.com

Date of release: 24 May 2018